

Yuefeng Li

List of Publications by Year in descending order

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8
papers

27
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1936888

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2053342

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8
times ranked

10
citing authors

#	ARTICLE	IF	CITATIONS
1	Effect of the Welding Process on the Microstructure and Mechanical Properties of Au/Sn-3.0Ag-0.5Cu/Cu Solder Joints. <i>Journal of Electronic Materials</i> , 2022, 51, 1597-1607.	1.0	6
2	Thermal conductivity anisotropy of expanded graphite/ chlorate salt composites for thermal energy storage. <i>Soft Materials</i> , 2021, 19, 78-88.	0.8	2
3	Effect of Different Soldering Temperatures on the Solder Joints of Flip-Chip LED Chips. <i>Journal of Electronic Materials</i> , 2021, 50, 796-807.	1.0	2
4	Effect of Soldering Temperature on the Reliability of Sn-Ag-Cu Lead-Free Solder Joints. <i>Journal of Electronic Materials</i> , 2021, 50, 869-880.	1.0	7
5	Effect of grain size on the interface structure and shear behavior of lead-free solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2021, 32, 21620-21630.	1.1	0
6	Research on Microstructure and Shear Behavior of Au/Sn-Ag-Cu/Cu Lead-free Solder Joints at Different Soldering Temperatures. <i>Journal of Electronic Materials</i> , 2021, 50, 5965-5980.	1.0	1
7	Research on the Mechanical and Performance Effects of Flux on Solder Layer Interface Voids. <i>Journal of Electronic Materials</i> , 2021, 50, 6629-6638.	1.0	4
8	The Effect of Different Filament Arrangements on Thermal and Optical Performances of LED Bulbs. <i>Applied Sciences (Switzerland)</i> , 2020, 10, 1373.	1.3	5